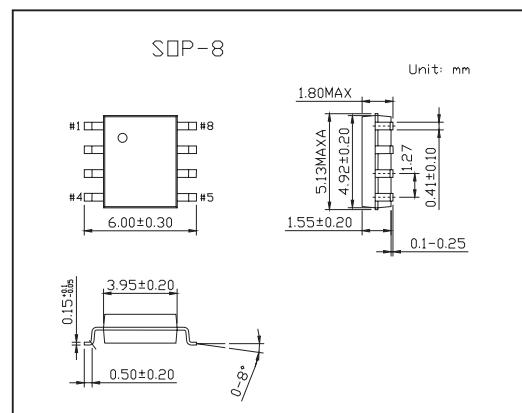
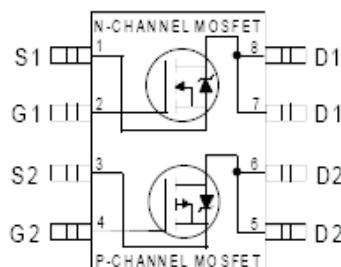


HEXFET® Power MOSFET

KRF7319

■ Features

- Generation V Technology
- Ultra Low On-Resistance
- Dual N and P Channel MOSFET
- Surface Mount
- Fully Avalanche Rated



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V _{DS}	30	-30	V
Continuous Drain Current *5 Ta = 25°C	I _D	6.5	-4.9	A
Continuous Drain Current *5 Ta = 70°C	I _D	5.2	-3.9	
Pulsed Drain Current	I _{DM}	30	-30	
Continuous Source Current (Diode Conduction)	I _S	2.5	-2.5	
Power Dissipation @Ta= 25°C *4	P _D	2.0		W
Power Dissipation @Ta= 70°C *4	P _D	1.3		
Single Pulse Avalanche Energy	E _{AS}	82	140	mJ
Avalanche Current	I _{AR}	4.0	-2.8	A
Repetitive Avalanche Energy	E _{AR}	0.20		mJ
Peak Diode Recovery dv/dt *2	dv/dt	5.0	-5	V/ ns
Gate-to-Source Voltage	V _{GSS}	±20		V
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to + 150		°C
Maximum Junction-to-Ambient *4	R _{θ JA}	62.5		°C/W

*1 Repetitive rating; pulse width limited by max. junction temperature.

*2 N-Channel I_{SD} ≤ 4.0A, di/dt ≤ 74A/ μ s, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C

P-Channel I_{SD} ≤ -2.8A, di/dt ≤ 150A/ μ s, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 150°C

*3 N-Channel Starting T_J = 25°C, L = 10mH R_G = 25Ω, I_{AS} = 4.0A.

P-Channel Starting T_J = 25°C, L = 35mH R_G = 25Ω, I_{AS} = -2.8A.

*4 Surface mounted on FR-4 board, t ≤ 10sec.

KRF7319■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Testconditons			Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250 \mu\text{A}$	N-Ch	30				V
		$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = -250 \mu\text{A}$		-30				
Breakdown Voltage Temp. Coefficient	$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	$I_{\text{D}} = 1\text{mA}, \text{Reference to } 25^\circ\text{C}$	N-Ch		0.022			$\text{V}/^\circ\text{C}$
		$I_{\text{D}} = -1\text{mA}, \text{Reference to } 25^\circ\text{C}$			0.022			
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 5.8\text{A}*1$	N-Ch		0.023	0.029		Ω
		$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 4.7\text{A}*1$			0.032	0.046		
		$V_{\text{GS}} = -10\text{V}, I_{\text{D}} = -4.9\text{A}*1$	P-Ch		0.042	0.058		
		$V_{\text{GS}} = -4.5\text{V}, I_{\text{D}} = -3.6\text{A}*1$			0.076	0.098		
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250 \mu\text{A}$	N-Ch	1.0				V
		$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = -250 \mu\text{A}$		-1.0				
Forward Transconductance	g_{fs}	$V_{\text{DS}} = 15\text{V}, I_{\text{D}} = 5.8\text{A}*1$	N-Ch		14			S
		$V_{\text{DS}} = -15\text{V}, I_{\text{D}} = -4.9\text{A}*1$			7.7			
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$	N-Ch			1.0		μA
		$V_{\text{DS}} = -24\text{V}, V_{\text{GS}} = 0\text{V}$				-1.0		
		$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$	N-Ch			25		
		$V_{\text{DS}} = -24\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$				-25		
Gate-to-Source Forward Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	N-Ch			± 100		nA
						± 100		
Total Gate Charge	Q_g	<p>N-Channel $I_{\text{D}} = 5.8\text{A}, V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}$</p> <p>P-Channel $I_{\text{D}} = -4.9\text{A}, V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = -10\text{V}$</p>	N-Ch		22	33	nC	
Gate-to-Source Charge	Q_{gs}			P-Ch		23	34	
Gate-to-Drain ("Miller") Charge	Q_{gd}		N-Ch		2.6	3.9		
				P-Ch		3.8	5.7	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	<p>N-Channel $V_{\text{DD}} = 15\text{V}, I_{\text{D}} = 1.0\text{A}, R_{\text{G}} = 6.0 \Omega$</p> <p>P-Channel $R_{\text{D}} = 15 \Omega$</p> <p>N-Channel $V_{\text{DD}} = -28\text{V}, I_{\text{D}} = -1.0\text{A}, R_{\text{G}} = 6.0 \Omega$</p> <p>P-Channel $R_{\text{D}} = 15 \Omega$</p>	N-Ch		6.4	9.6	ns	
				P-Ch		5.9	8.9	
Rise Time	t_r		N-Ch		8.1	12		
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			P-Ch		13	19	
Fall Time	t_f		N-Ch		8.9	13		
Input Capacitance	C_{iss}	<p>N-Channel $V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$</p> <p>P-Channel $V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -25\text{V}, f = 1.0\text{MHz}$</p>	N-Ch		26	39	pF	
				P-Ch		34	51	
Output Capacitance	C_{oss}		N-Ch		17	26		
				P-Ch		32	48	
Reverse Transfer Capacitance	C_{rss}		N-Ch		650		pF	
				P-Ch		710		

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■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Continuous Source Current (Body Diode)	Is		N-Ch		2.5	A
			P-Ch		-2.5	
Pulsed Source Current (Body Diode) *2		TJ = 25°C, Is = 1.7A, VGS = 0V*1	N-Ch		30	
Diode Forward Voltage	VSD		P-Ch		-30	
Reverse Recovery Time	trr	N-Channel TJ = 25°C, IF = 1.7A, di/dt = 100A/μs*1 P-Channel TJ=25°C, IF=-1.7A, di/dt=-100A/μs*1	N-Ch	0.78	1.0	V
Reverse RecoveryCharge	Qrr		P-Ch	-0.78	-1.0	
			N-Ch	45	68	ns
			P-Ch	44	66	
			N-Ch	58	87	nC
			P-Ch	42	63	

*1 Pulse width ≤ 300 μ s; duty cycle ≤ 2%.

*2 Repetitive rating; pulse width limited by max. junction temperature.